



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND
WAFER SCALE INTERPOSER
SUBSTRATE MEMBER FOR USE WITH
FLIP-CHIP CONFIGURED
SEMICONDUCTOR DICE

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-4973.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 29, 2004
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 16 of this paper.

Remarks begin on page 21 of this paper.